

IN THE ABSTRACT:

Please replace the Abstract of the Disclosure with the text enclosed in clean form herein below pursuant to 37 C.F.R. §§ 1.121(b)(1)(i) and 1.121(b)(1)(ii). Also attached is a marked-up version of the same Abstract, as amended herein, pursuant to 37 C.F.R. § 1.121(b)(1)(iii).

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Methods for placing conductive spheres on prefluxed bond pads of a substrate using a stencil plate with a pattern of through-holes positioned over the bond pads. Conductive spheres are placed in the through-holes by a moving feed mechanism and the spheres drop through the through-holes onto the bond pads. In one embodiment, the feed mechanism is a sphere hopper which crosses the entire through-hole pattern. In another embodiment, a shuttle plate fed spheres from a reservoir and reversibly moves about one-half of the pitch, moving from a non-discharge position to a discharge position.